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	Total No. of Questions: 5] [Total No. of Printed Pages: 3
	Roll No
	EC-803(N)
	B. E. (Eighth Semester) EXAMINATION, June, 2011
	(Electronics and Communication Engg. Branch)
	NANOELECTRONICS
	[EC-803(N)]
	Time: Three Hours
	Maximum Marks: 100
	Minimum Pass Marks: 35
	Note: All questions are compulsory. Each question contains internal choice. All questions carry equal marks. 1. Give brief notes on the following:
	(i) Top down and bottom up approaches 8
	(ii) Applications of nanotechnology 6
	(iii) Effect of size on electronic properties of nano materials 6
	Or
	(i) How energy bands are formed?
	(ii) Why energy discreteness occurs in nano materials ? 7
	(iii) How does electrical conduction in metals, insulators and semiconductor differ?
	2. What is a Tunneling Diode (TD)? With appropriate circuit 'diagram, explain the implementation of any one of the following application using single TD: Counter/Frequency

divider/A/D converter (If needed use other components such as NAND, NOR, transistor, etc). 5, 15.

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When will you call a semiconductor as bulk, quantum well, quantum wire, quantum dot or nanoparticle? Discuss in terms of density of states, electronic properties, optical properties, energy level structure etc.

8, 12

3. What is Coulomb blockade? How Coulomb diamond structure is used to design a single electron transistor?

8, 12

Or

Show that the condition for an electron to tunnel from positive terminal to negative terminal in a capacitor is V < qe/2 C.

4. Obtain an expression for current flow in a ballastic conductor. Consider a 20 nm length of a ballastic conductor carrying N = 4 electron modes. Determine the current that will flow if a 0.3 V potential difference is applied across the length of conductor. Assume low temperature and T_n = 1.

Or

With appropriate sketch, explain your understanding on the following:

- (i) Fullerene
- (ii) Diamond Like Carbon (DLC)
- (iii) Molecular shift register using biomolecules 6

- Describe the following nanomaterial fabrication technologies:
 - (i) Plasma Enhanced Chemical Vapor Deposition (PECVD)
 - (ii) Pulsed Laser Deposition (PLD)

Or'

To fabricate a semiconductor heterostructure (example GaAs/GaAlAs), suggest a lithographic and a non-lithographic technique. Discuss with suitable diagram of various steps involved in fabricating the heterostructure.

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